

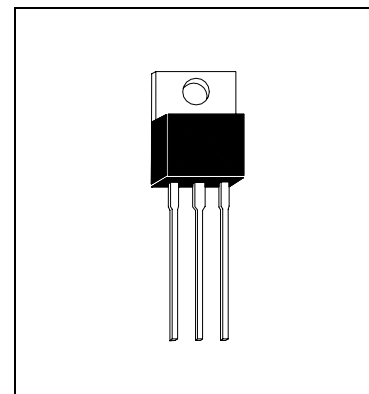


H2585

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The H2585 is designed for use in low voltage and low drop out regulator applications.



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 40 W
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -20 V
VCEO Collector to Emitter Voltage -15 V
VEBO Emitter to Base Voltage -5 V
IC Collector Current -5 A

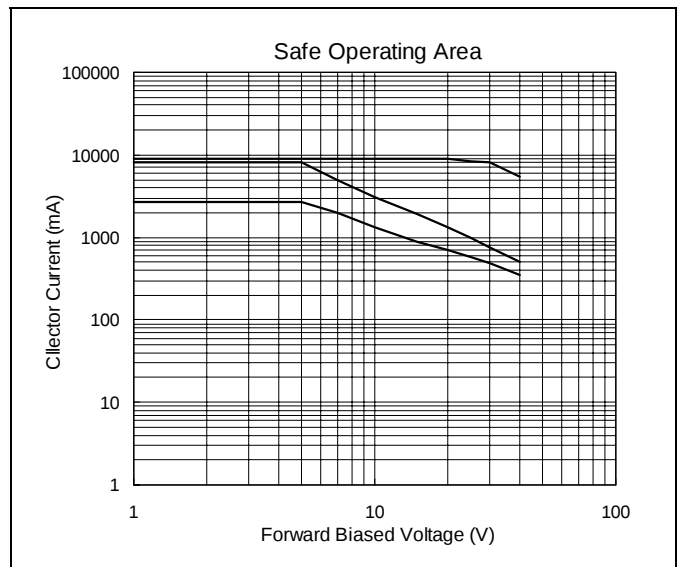
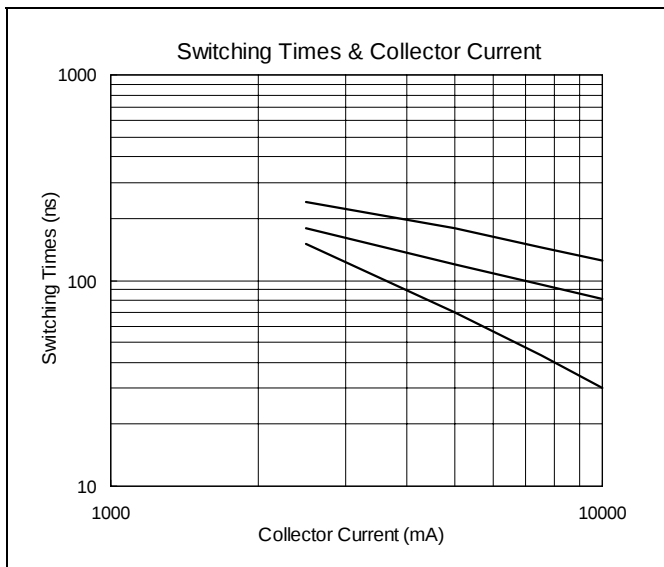
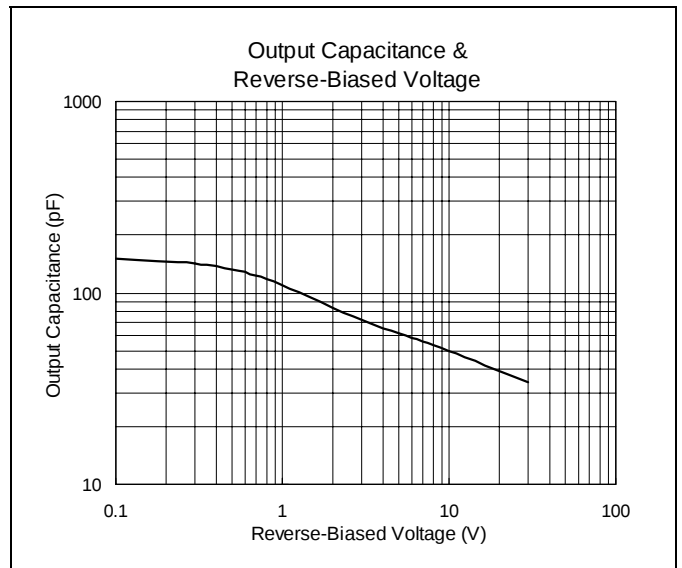
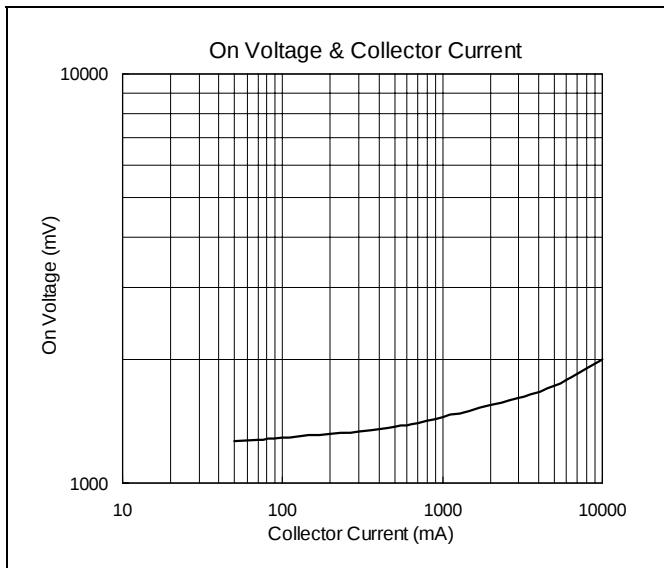
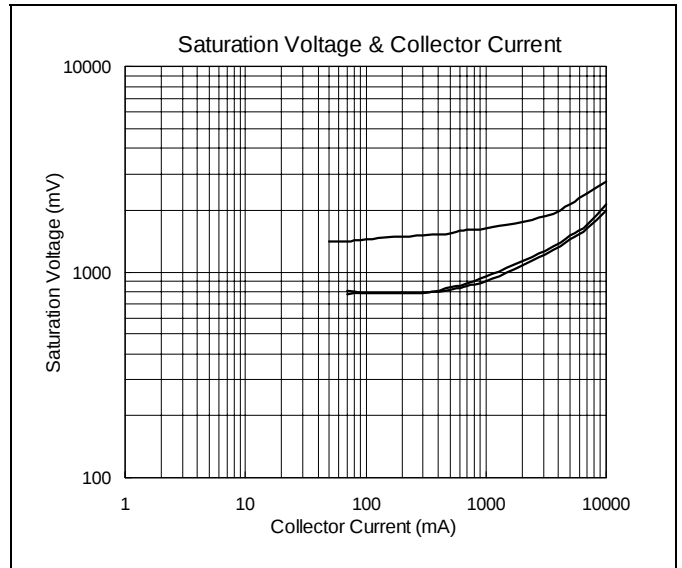
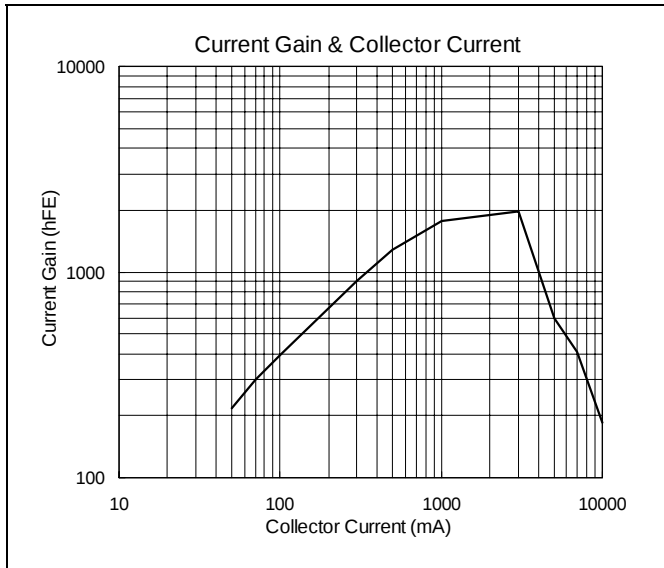
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
*BVCEO	-15	-	-	V	IC=-100mA
BVCBO	-20	-	-	V	IC=-10mA
ICBO	-	-	-10	uA	VCB=-20V
ICEO	-	-	-20	uA	VCE=-15V
IEBO	-	-	-2	mA	VEB=-5V
*VCE(sat)1	-	-	-1.5	V	IC=-3A, IB=-3mA
*VCE(sat)2	-	-	-1.5	V	IC=-5A, IB=-5mA
VBE(on)	-	-	-2	V	IC=-3A, VCE=-1.7V
*hFE1	1	-	60	K	IC=-500mA, VCE=-1.7V
*hFE2	1	-	60	K	IC=-5A, VCE=-1.7V
Cob	-	-	100	pF	VCB=-10V

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

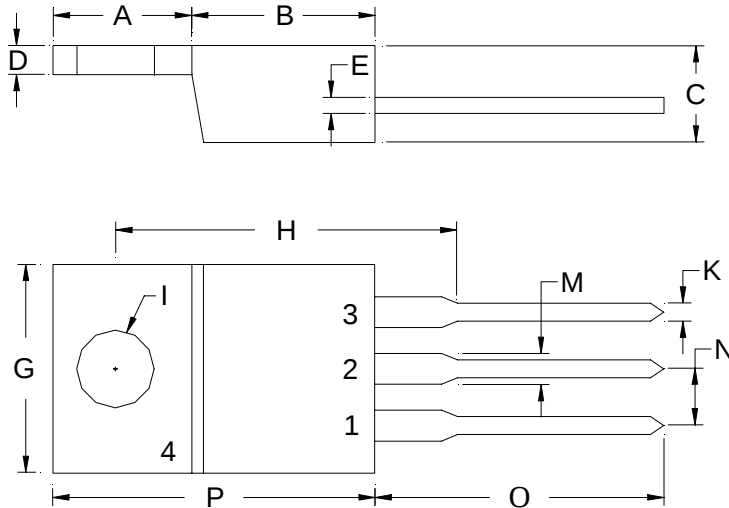


Characteristics Curve

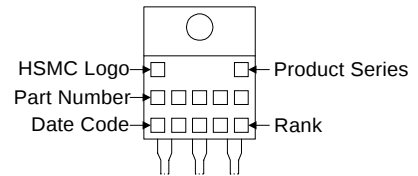




TO-220AB Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-220AB Plastic Package
HSMC Package Code : E

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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